

WIRING BOARD

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- international: **H05K1/11; H05K3/46; H05K1/11; H05K3/46; (IPC1-7): H05K1/11; H05K3/46**

- European:

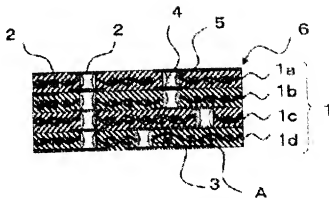
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Abstract of JP2002141628

PROBLEM TO BE SOLVED: To solve the problem that intervals in a through hole cannot be set to 300 μ m or less since migration due to a metal ion is generated between feed-through conductors. **SOLUTION:** This wiring board 6 has a plurality of insulating layers 1a to 1d where an organic resin is dipped into a glass fiber base A, a circuit conductor layer 2 provided on the surface of the insulating layers 1a to 1d and between the layers, a resin layer 5 that is formed on the internal wall of the through hole 3 punched in the insulating layers 1a to 1d and covers the end section of the glass fiber base A exposed onto the internal wall, and the feed-through conductor 4 that is filled into the inside of the through hole 3 and electrically connects the circuit conductor layers 2 positioned above and below. In the resin layer 5, the maximum thickness should be provided in a region of $\pm 40\%$ in a depth wise direction with a site having 1/2 the depth of the through hole 3 as a center. The migration of the metal ion between the feed-through conductors 4 is



prevented effectively, thus preventing the generation of ion migration.

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